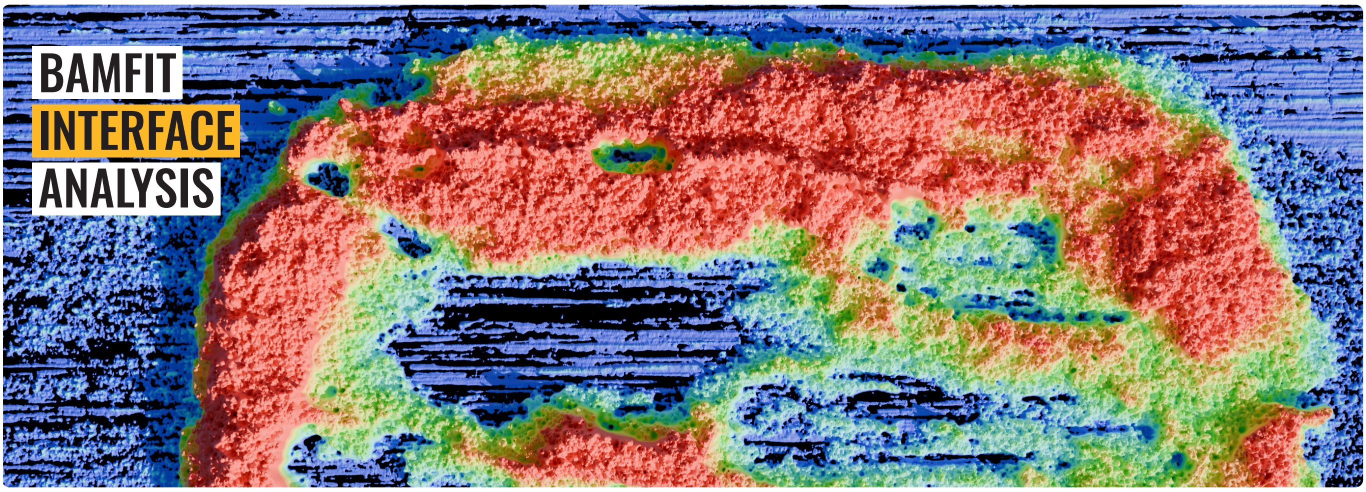


BAMFIT INTERFACE ANALYSIS

New wire materials, higher operating temperatures, changing chip designs, tighter tolerances.

CUSTOMER DEMANDS ARE RISING, VALIDATION EFFORTS ARE EXPLODING.

DO YOUR TEST METHODS DELIVER BETTER ANSWERS?

New wire materials, higher operating temperatures, changing chip designs, tighter tolerances. The demands on your bond connections are growing.

Customers today expect more detailed evidence of connection quality than just a few years ago. At the same time, corrosion-resistant alloys and optimized microstructures are entering the market. And development cycles are getting shorter: decisions about process parameters and material selection must be made faster, often without the opportunity to test and optimize for months.

In this environment, the classic shear test reaches its limits. It delivers a force - but this number alone says little about what actually happened in the bond interface. A high shear force can indicate a homogeneous connection, but it can equally be the result of excessive deformation. And the fracture pattern after the shear test? Smeared material covers exactly the areas you actually want to evaluate.

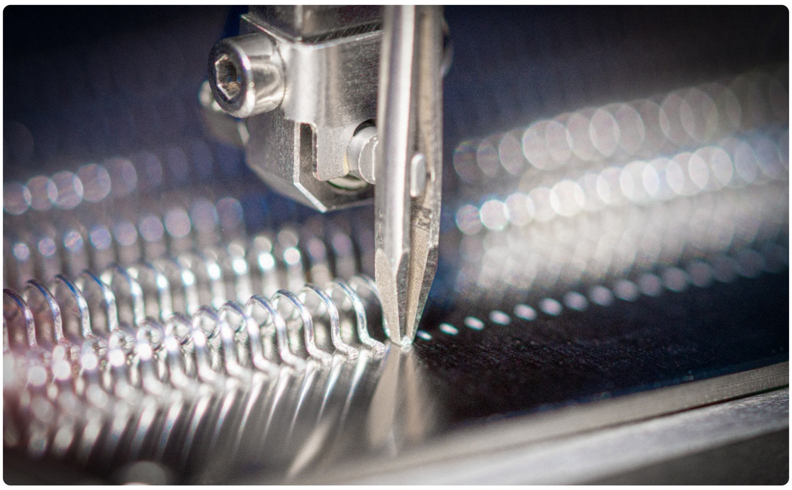
For well-founded decisions under time pressure, the crucial information is often missing: How much area is actually bonded - and how uniformly is this connection formed?

OUR SOLUTION: BAMFIT INTERFACE ANALYSIS

With the **BAMFIT method**, we expose the bond interface cleanly, without smearing material. The subsequent analysis using light microscopy and 3D topography enables precise quantification of the actually bonded area. Unbonded regions, defects and inhomogeneities become visible and measurable.

WHAT THIS MEANS FOR YOU:

- ✓ **Well-founded material decisions**
  Compare new wire materials not just by shear forces, but based on real interface data.
- ✓ **Faster process optimization**
  Immediately see how parameter changes affect bond formation.
- ✓ **Reliable data for demanding customers**
  Document your bond quality at a level that goes beyond standard testing.
- ✓ **Early detection of weak points**
  Identify potential reliability risks in your daily production before they become problems.



STOP GUESSING. HERE'S HOW.

1. **Send us your samples**
   Ship your wire bonding samples to our lab — we handle everything from there.
2. **Advanced BAMFIT Analysis**
   Our experts expose and analyze the bond interface using light microscopy and 3D topography.
3. **Actionable results, delivered**
   Receive quantified area data, high-resolution images, and a full evaluation report.

SEND US YOUR SAMPLES AND GAIN THE INSIGHTS THAT THE SHEAR TEST CANNOT PROVIDE.

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Stay connected and be a part of our growing network. Follow us on LinkedIn for industry updates, subscribe to our newsletter for expert tips and news, or join us at our virtual wire bonding roundtable to network with peers and expand your knowledge.

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